

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: : Customer Number: 89518  
: :  
Mou-Shiung Lin : Confirmation Number: 8665  
: :  
Application No.: 10/755,042 : Group Art Unit: 2815  
: :  
Filed: January 9, 2004 : Examiner: Jackson Jr, Jerome  
: :  
For: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND  
METHOD OF MANUFACTURING THE SAME

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATE OF ELECTRONIC TRANSMISSION**  
I hereby certify that this correspondence is being electronically-  
transmitted to the United States Patent and Trademark Office on  
**November 16, 2009.**  
/Tobi A. Terry/  
\_\_\_\_\_  
Tobi A. Terry

**RESPONSE/AMENDMENT**

Sir:

In response to the Office Action dated June 16, 2009, the Applicant respectfully requests further examination of the above-identified application in light of the following:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Amendments to the Drawings** begin on page 9 of this paper and include an attached replacement sheet.

**Remarks/Arguments** begin on page 10 of this paper.

A Replacement Sheet including amended drawings figures is attached following page 17 of this paper.